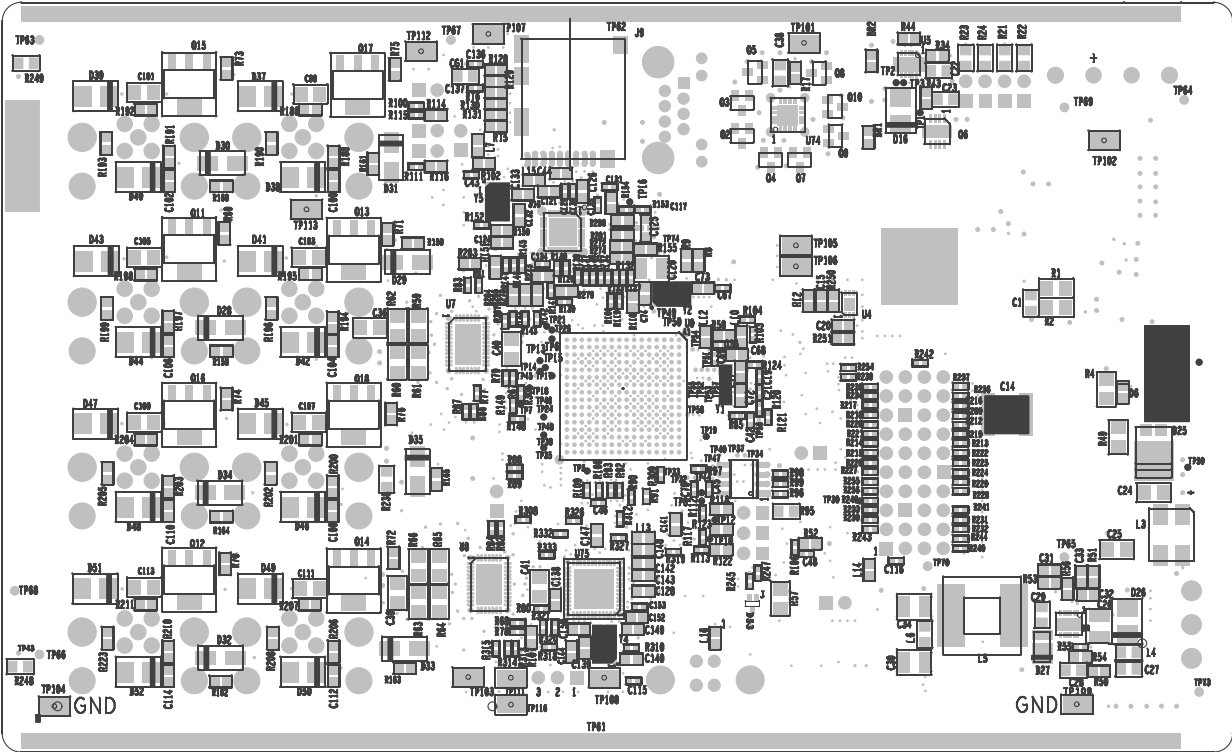



REVISION HISTORY				
ECO	REV	DESCRIPTION	APPROVED	DATE
-	3	3RD PROTOTYPE	KEITH B.	12-2-14

NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER SMD BOTH SIDES. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
5. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.



APPROVALS		<div>  <div> 1630 McCarthy Blvd. Milpitas, CA 95035 Phone: (408) 432-1900 Fax: (408) 434-0507 www.linear.com </div> <div> LTC CONFIDENTIAL FOR CUSTOMER USE ONLY </div> </div>		
PCB DES.	TECONCEPT			
APP ENG.	KEITH B.	TITLE: TOP ASSEMBLY DRAWING IO-LINK DEMONSTRATOR		
		SIZE	IC NO.	REV.
		N/A	LTC2874IUHF DEMO CIRCUIT 2228A	3
SCALE = 1:1		DATE: Tuesday December 2, 2014		SHEET 1 OF 1